



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20180308002
Transfer of select VIP3 devices from GFAB to DFAB Wafer Fab site
Change Notification / Sample Request

Date: March 09, 2018
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

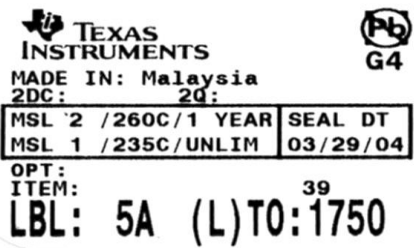
20180308002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM6171BIN/NOPB	null
LM7171BIN/NOPB	null
LM7321MAX/NOPB	null
LMH6321MR/NOPB	null
LM6171BIMX/NOPB	null
LM6172IMX/NOPB	null
LM6172IM/NOPB	null
LM7322MME/NOPB	null
LM8262MM/NOPB	null
LMH6321TSX/NOPB	null
LM7121IM/NOPB	null
LM7121IM5/NOPB	null
LME49720MAX/NOPB	null
LM7341MFE/NOPB	null
LME49600TS/NOPB	null
LME49724MR/NOPB	null
LM7301IM5/NOPB	null
LM7332MM/NOPB	null
LME49860MAX/NOPB	null
LM7171BIM/NOPB	null
LM7121IM5X/NOPB	null
LM8261M5/NOPB	null
LM7171BIMX/NOPB	null
LM7372MRX/NOPB	null
LM4562MAX/NOPB	null
LM7321MFX/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180308002		PCN Date:	Mar 9, 2018																			
Title:	Transfer of select VIP3 devices from GFAB to DFAB Wafer Fab site																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Jun 9, 2018		Estimated Sample Availability:	Date provided at sample request.																			
Change Type:																							
☐ Assembly Site	☐ Assembly Process	☐ Assembly Materials																					
☐ Design	☐ Electrical Specification	☐ Mechanical Specification																					
☐ Test Site	☐ Packing/Shipping/Labeling	☐ Test Process																					
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process																					
☒ Wafer Fab Site	☒ Wafer Fab Materials	☐ Wafer Fab Process																					
	☐ Part number change																						
PCN Details																							
Description of Change:																							
This change notification is to announce the transfer of select VIP3 devices from GFAB to the DFAB (DL-LIN) Wafer Fab site for the selected devices listed in the "Product Affected" section.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">New Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>New Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>GFAB6</td> <td>VIP3</td> <td>150 mm</td> <td>DL-LIN</td> <td>VIP3</td> <td>200 mm</td> </tr> </tbody> </table>						Current Fab Site			New Fab Site			Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter	GFAB6	VIP3	150 mm	DL-LIN	VIP3	200 mm
Current Fab Site			New Fab Site																				
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter																		
GFAB6	VIP3	150 mm	DL-LIN	VIP3	200 mm																		
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Greenock, Scotland (GFAB) Wafer Fab site closure																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
Current:																							
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
GFAB6	GF6	GBR	Greenock																				
New Fab Site:																							
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
DL-LIN	DLN	USA	Dallas																				
Sample product shipping label (not actual product label)																							
  (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS																							
Product Affected:																							
5962F9560401V9A	LM7121IMX/NOPB	LM7322MA/NOPB	LM8262MM/NOPB																				
LM4562MA/NOPB	LM7171AIM	LM7322MAX/NOPB	LM8262MMX/NOPB																				
LM4562MA/S7002211	LM7171AIM/NOPB	LM7322MM/NOPB	LM8272MM																				
LM4562MAX/NOPB	LM7171AIMX/NOPB	LM7322MME/NOPB	LM8272MM/NOPB																				
LM4562NA/NOPB	LM7171BIM	LM7332MA/NOPB	LM8272MMX/NOPB																				

LM6171AIM	LM7171BIM/NOPB	LM7332MAX/NOPB	LME49600TS/NOPB
LM6171AIM/NOPB	LM7171BIMX/NOPB	LM7332MM/NOPB	LME49720MAX/NOPB
LM6171AIMX/NOPB	LM7171BIN/NOPB	LM7332MME/NOPB	LME49720NA/NOPB
LM6171BIM	LM7301IM	LM7332MMX/NOPB	LME49724MA/NOPB
LM6171BIM/NOPB	LM7301IM/NOPB	LM7341MF/NOPB	LME49724MR/NOPB
LM6171BIMX/NOPB	LM7301IM5	LM7341MFE/NOPB	LME49724MRX/NOPB
LM6171BIN/NOPB	LM7301IM5/NOPB	LM7341MFX/NOPB	LME49860MAX/NOPB
LM6172 MDR	LM7301IM5X	LM7372IMA	LMH6321MR/NOPB
LM6172IM	LM7301IM5X/NOPB	LM7372IMA/NOPB	LMH6321MRX/NOPB
LM6172IM/NOPB	LM7301IM5X/S5000655	LM7372IMAX/NOPB	LMH6321TS/NOPB
LM6172IMX	LM7301IM5X/S7000823	LM7372MR/NOPB	LMH6321TSX/NOPB
LM6172IMX/E7001904	LM7301IM5X/SL110603	LM7372MRX	TLV87321DBVR
LM6172IMX/NAK2	LM7301IMX/E7002184	LM7372MRX/NOPB	TLV87321DBVT
LM6172IMX/NOPB	LM7301IMX/NOPB	LM8261M5	TLV87321DR
LM6172IN/NOPB	LM7321MA/NOPB	LM8261M5/NOPB	TLV87321DT
LM7121IM	LM7321MAX/NOPB	LM8261M5X	TLV87322DGKR
LM7121IM/NOPB	LM7321MF/NOPB	LM8261M5X/J7002376	TLV87322DGKT
LM7121IM5	LM7321MFE/NOPB	LM8261M5X/NOPB	TLV87322DR
LM7121IM5/NOPB	LM7321MFX/NOPB	LM8262MM	TLV87322DT
LM7121IM5X/NOPB			

Qualification Report

VIP3 Qualification at DFAB

Approve Date 06-Mar-2018

Product Attributes

Attributes	Qual Device: LM6172IM/NOPB
Assembly Site	TIEMA
Package Family	SOIC
Flammability Rating	1
Wafer Fab Supplier	DFAB 200MM
Wafer Process	VIP3

- Qual Devices qualified at LEVEL1-260CG: LM6172IM/NOPB

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM6172IM/NOPB
AC	Autoclave 121C	96 Hours	3/231/0
ED	Electrical Distributions	Cpk>1.67 Room, Hot, & Cold	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
MQ	Manufacturability (Auto Assembly)	(per automotive requirements)	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
WBP	Post Temp. Cycle, Bond Pull	500 Cycles	3/15/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com